Title (en)

NICKEL PARTICLE COMPOSITION, BONDING MATERIAL, AND BONDING METHOD IN WHICH SAID MATERIAL IS USED

Title (de)

NICKELPARTIKELZUSAMMENSETZUNG, BINDEMATERIAL UND BINDEVERFAHREN, IN DEM DAS BESAGTE BINDEMATERIAL VERWENDET WIRD

Title (fr)

COMPOSITION DE PARTICULES DE NICKEL, MATÉRIAU LIANT ET PROCÉDÉ DE LIAISON FAISANT APPEL AUDIT MATÉRIAU

Publication

EP 3162467 A1 20170503 (EN)

Application

EP 15815115 A 20150630

Priority

- JP 2014135245 A 20140630
- JP 2015068757 W 20150630

Abstract (en)

A nickel particle composition is provided, including: A) a nickel particle having an average particle size in the range of 0.5 μm to 20 μm obtained via a laser diffraction/scattering method and containing 50 wt% or more of a nickel element; B) a nickel fine particle having an average primary particle size in the range of 30 nm to 200 nm observed via a scanning electron microscope and containing 50 wt% or more of a nickel element; and C) an organic binder in the range of 0.1 wt% to 2.5 wt% relative to the total metal content; and the weight ratio of a component A to a component B (component A: component B) is in the range of 30:70 to 70:30.

IPC 8 full level

B22F 1/052 (2022.01); **B22F 1/107** (2022.01); **B22F 3/02** (2006.01); **B22F 7/04** (2006.01); **B22F 7/08** (2006.01); **B22F 9/24** (2006.01); **B23K 20/00** (2006.01); **B23K 35/22** (2006.01); **B23K 35/30** (2006.01); **C22C 19/03** (2006.01); **H01B 1/00** (2006.01); **H01B 1/22** (2006.01); **H01L 21/52** (2006.01); **H01L 23/373** (2006.01)

CPC (source: EP US)

B22F 1/052 (2022.01 - EP US); **B22F 1/107** (2022.01 - EP US); **B23K 1/0016** (2013.01 - US); **B23K 20/00** (2013.01 - EP US); **B23K 35/0244** (2013.01 - EP US); **B23K 35/025** (2013.01 - EP US); **B23K 35/22** (2013.01 - US); **B23K 35/30** (2013.01 - US); **B23K 35/3033** (2013.01 - EP US); **B23K 35/3612** (2013.01 - EP US); **B23K 35/3613** (2013.01 - EP US); **B23K 35/3615** (2013.01 - EP US); **H01B 1/22** (2013.01 - EP US); **H01L 21/52** (2013.01 - EP US); **H01L 23/373** (2013.01 - EP US); **H01L 24/29** (2013.01 - US); **H01L 24/32** (2013.01 - US); **H01L 24/83** (2013.01 - US); B22F 7/08 (2013.01 - EP US); B22F 9/24 (2013.01 - EP US); B22F 2301/15 (2013.01 - US); B22F 2302/45 (2013.01 - US); B22F 2304/054 (2013.01 - US); B22F 2304/056 (2013.01 - US); B22F 2304/10 (2013.01 - US); C22C 19/03 (2013.01 - EP US); H01L 2224/29155 (2013.01 - US); H01L 2224/83065 (2013.01 - US); H01L 2224/832 (2013.01 - US); H01L 2924/0002 (2013.01 - EP US); H01L 2924/20106 (2013.01 - US); H01L 2924/20107 (2013.01 - US); H01L 2924/20108 (2013.01 - US); H01L 2924/20109 (2013.01 - US); H01L 2924/2011 (2013.01 - US)

Designated contracting state (EPC)

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DOCDB simple family (application)

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